

## ABSTRACT OF THE DISCLOSURE

The present invention relates to method to improve RF measurements accuracy on an automatic testing equipment (ATE) for IC wafers by implementing a test board de-embedding phase, wherein each wafer includes a device under test located on a wafer die plane and being contacted by probecard needles of a probecard that is coupled to a configuration board through a probe interface board (PIB), the method including the following phases: performing an automatic calibration phase of the testing equipment up to an internal plane located inside the automatic testing equipment; performing a calibration plane transfer up to a plane of the configuration board using a predetermined number of calibration standard loads realized on the wafer; performing a test boards de-embedding phase up to the wafer die plane.

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